

## NCE N-Channel Enhancement Mode Power MOSFET

## **Description**

The NCE30H14K uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

#### **General Features**

V<sub>DS</sub> =30V,I<sub>D</sub> =140A

 $R_{DS(ON)}$  <3.0m $\Omega$  @  $V_{GS}$ =10V

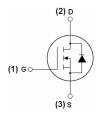
 $R_{DS(ON)}$  <3.6m $\Omega$  @  $V_{GS}$ =4.5V

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E<sub>AS</sub>
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

#### **Application**

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED!
100% ΔVds TESTED!



#### Schematic diagram



#### Marking and pin assignment



TO-252-2L top view

## **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE30H14K	NCE30H14K	TO-252-2L	-	-	-

Absolute Maximum Ratings (T<sub>A</sub>=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	I <sub>D</sub>	140	Α
Drain Current-Continuous(T <sub>C</sub> =100°C)	I <sub>D</sub> (100℃)	99	Α
Pulsed Drain Current	I <sub>DM</sub>	400	Α
Maximum Power Dissipation	P <sub>D</sub>	130	W
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	400	mJ
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 175	°C

#### **Thermal Characteristic**

Thermal Resistance,Junction-to-Case <sup>(Note 2)</sup>	R <sub>eJC</sub>	1.25	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	50	°C/W



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# Electrical Characteristics (T<sub>A</sub>=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics	•		•				
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	30	-	-	V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V	-	-	1	μA	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA	
On Characteristics (Note 3)	•		•				
Gate Threshold Voltage	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	1	1.6	2.5	V	
Drain-Source On-State Resistance		V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	2.5	3.0	mΩ	
Dialii-30uice Oii-3tate Resistance	$R_{DS(ON)}$	V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	2.9	3.6	11122	
Gate resistance	R <sub>G</sub>		-	1.6	-	Ω	
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =5V,I <sub>D</sub> =20A	50	-	-	S	
Dynamic Characteristics (Note4)							
Input Capacitance	C <sub>lss</sub>	\/ -45\/\/ -0\/		3780		PF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =15V,V <sub>GS</sub> =0V, F=1.0MHz		448		PF	
Reverse Transfer Capacitance	C <sub>rss</sub>	F-1.UIVITZ		410		PF	
Switching Characteristics (Note 4)	•		•				
Turn-on Delay Time	t <sub>d(on)</sub>		-	12	-	nS	
Turn-on Rise Time	t <sub>r</sub>	V <sub>GS</sub> =10V,V <sub>DS</sub> =15V	-	16	-	nS	
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_L$ =0.75 $\Omega$ , $R_{GEN}$ =3 $\Omega$	-	42	-	nS	
Turn-Off Fall Time	t <sub>f</sub>		-	12	-	nS	
Total Gate Charge	Qg			80		nC	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> =10V,V <sub>DS</sub> =15V,I <sub>D</sub> =20A		12.4		nC	
Gate-Drain Charge	$Q_{gd}$			18.3		nC	
Drain-Source Diode Characteristics	•		•				
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =20A	-	-	1.2	V	
Diode Forward Current (Note 2)	Is	-		-	140	Α	
Reverse Recovery Time	t <sub>rr</sub>	TJ = 25°C, I <sub>F</sub> =20A	-	58	-	nS	
Reverse Recovery Charge	Qrr	di/dt = 100A/µs <sup>(Note3)</sup>	-	115	-	nC	
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)					

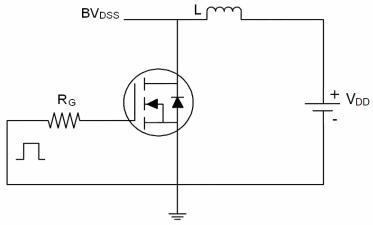
#### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. The value of  $R_{BJA}$  is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A$  =25° C. The Power dissipation  $P_{DSM}$  is based on  $R_{BJA}$  and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design, and the maximum temperature of 175° C may be used if the PCB allows it.
- **3.** Pulse Test: Pulse Width ≤  $300\mu$ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- **5.** EAS condition: Tj=25  $^{\circ}\text{C}$  ,VDD=15V,VG=10V,L=0.5mH,Rg=25 $\Omega$

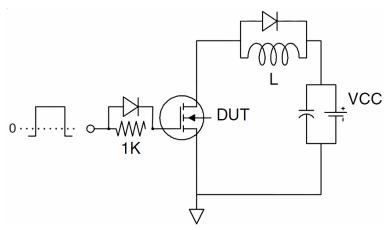


## **Test circuit**

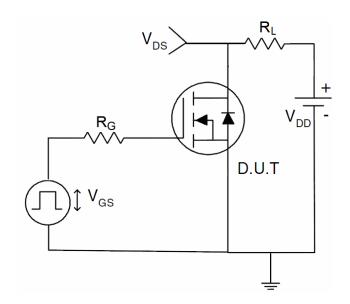
# 1) E<sub>AS</sub> test Circuits



# 2) Gate charge test Circuit:

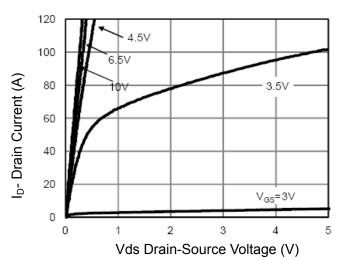


## 3) Switch Time Test Circuit:

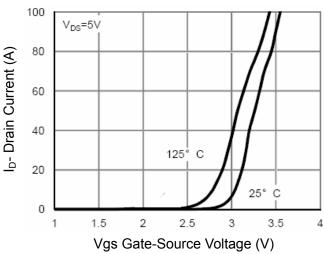




## Typical Electrical and Thermal Characteristics (Curves)



**Figure 1 Output Characteristics** 



**Figure 2 Transfer Characteristics** 

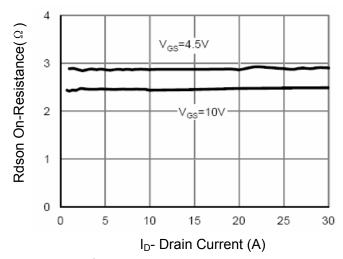
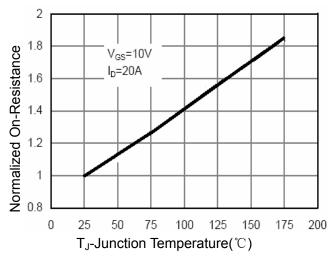


Figure 3 Rdson- Drain Current



**Figure 4 Rdson-Junction Temperature** 

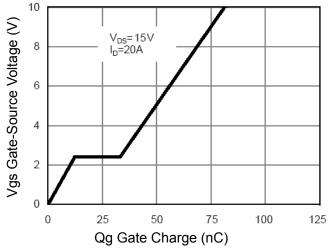


Figure 5 Gate Charge

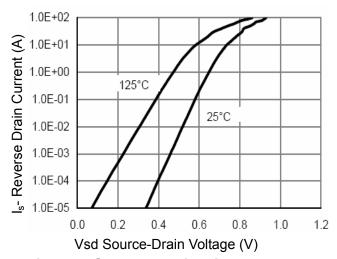


Figure 6 Source- Drain Diode Forward



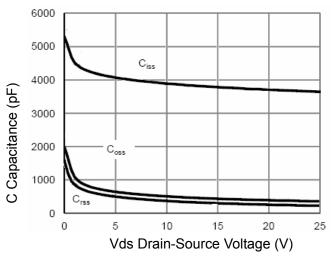
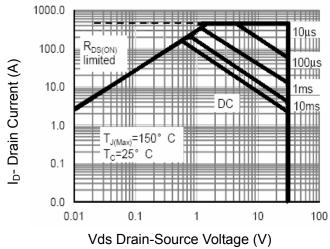


Figure 7 Capacitance vs Vds



**Figure 8 Safe Operation Area** 

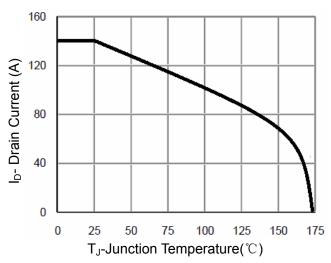


Figure 9 Current De-rating

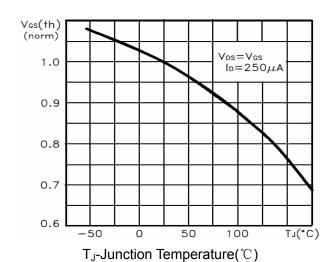
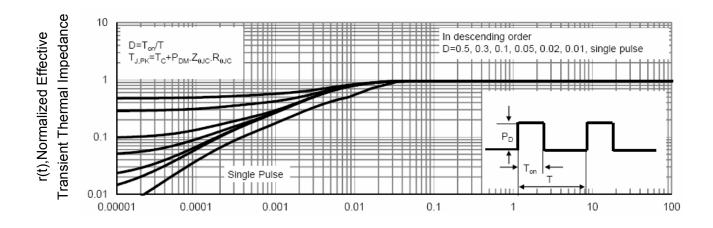


Figure 10 V<sub>GS(th)</sub> vs Junction Temperature

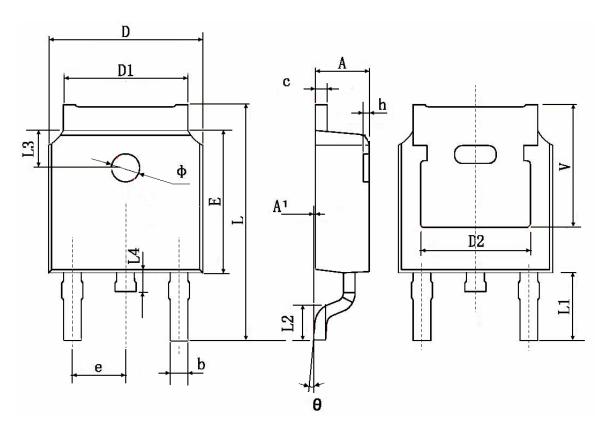


Square Wave Pluse Duration(sec)

**Figure 11 Normalized Maximum Transient Thermal Impedance** 



# **TO-252 Package Information**



Comple al	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.83	TYP.	0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.90	0 TYP.	0.114	TYP.	
L2	1.400	1.700	0.055	0.067	
L3	1.60	00 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.35	5.350 TYP. 0.211 TYP.			

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# NCE30H14K

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